深圳康比电子有限公司

KANGBI TECHNOLOGY INDUSTRY CO.,LTD.

产品规格书

SAMPLE APPROVAL SHEET

CUSTOMER客户: _____

SIZE UP规格: F11 -DIP

MODEL型号: R330M

NUMBER数量: _____

DATE日期: _____

Customer's Approval Certificate

Please return this copy as a certification of Your approval

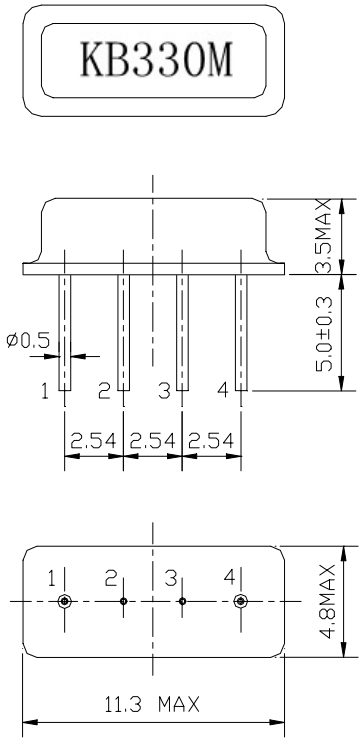
Checked & Approval by:

Date:

1. Package Dimension

(F-11)

Unit: mm



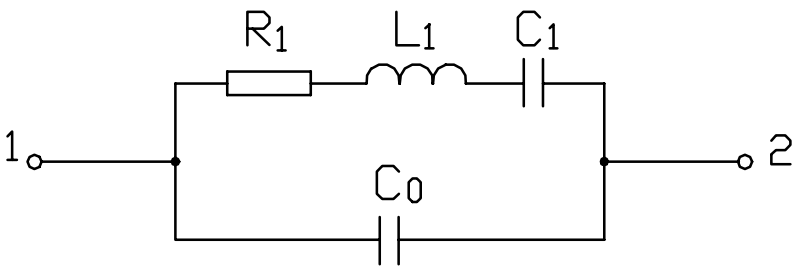
Pin No.	Function
1.	Input
2.	Ground
3.	Ground
4.	Output

2. Marking

KON 330.00

1. Color: Black or Blue
2. D: Manufacture's logo
3. R1: One-port SAW Resonator
4. 330.00: Center Frequency (MHz)

3. Equivalent LC Model



4. Performance

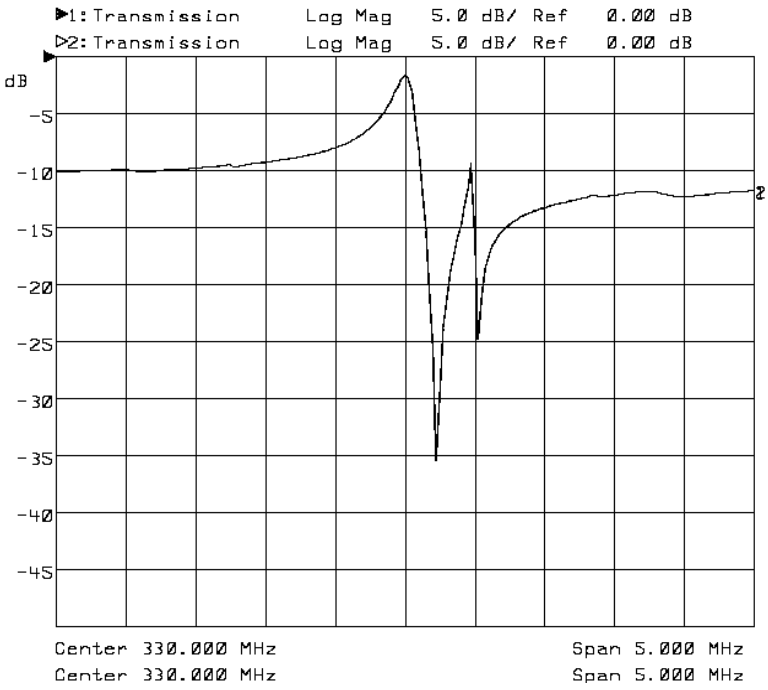
4.1 Maximum Rating

DC Voltage V_{DC}	10V
AC Voltage V_{PP}	10V (50Hz/60Hz)
Operation Temperature	-40 ℃ to +85℃
Storage Temperature	-45 ℃ to +85℃
RF Power Dissipation	0dBm

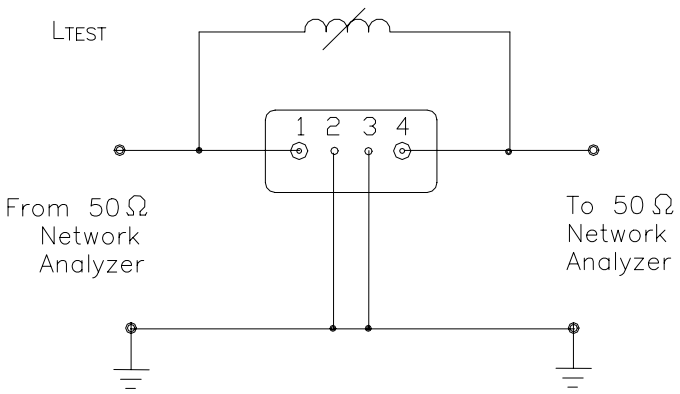
4.2 Electronic Characteristics

Item		Units	Minimum	Typical	Maximum
Center Frequency fo		MHz	329.925	330.00	330.075
Insertion Loss		dB	—	1.3	2.5
Quality Factor	Unloaded Q	—	—	10,700	—
	50Ω Loaded Q	—	—	2,000	—
Tem perature Stability	Turnover Temperature	℃	—	39	—
	Turnover Frequency	KHz	—	fo+2.7	—
	Freq. Temp. Coefficient	ppm/℃^{2}	—	0.032	—
Frequency Aging		ppm/yr	—	<±10	—
DC Insulation Resistance		MΩ	1.0	—	—
RF Equivalent RLC Model	Motional Resistance R_1	Ω	—	25	32
	Motional Inductance L_1	μH	—	130.92	—
	Motional Capacitance C_1	fF	—	1.78	—
	Shunt Static Capacitance C_O	pF	1.9	2.2	2.5

4.3 Frequency Characteristics



4.4 Test Circuit



Note: Reference temperature shall be 25±2℃. However, the measurement may be carried out at 5℃ to 35℃ unless there is a dispute.

5. Reliability

5.1 Mechanical Shock: The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s^2, duration 6 milliseconds.

5.2 Vibration Fatigue: The components shall remain within the electrical specifications after loaded vibration at 20 Hz, amplitude 1.5 mm, for 2 hours.

5.3 Terminal Strength: The components shall remain within the electrical specifications after pulled 2 kgs weight for 10 seconds towards an axis of each terminal.

5.4 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85℃±2℃ for 48 hours, then kept at room temperature for 2 hours.

5.5 Low Temperature Storage: The components shall remain within the electrical

specifications
after being kept at the -25℃±2℃ for 48 hours, then kept at room temperature for 2 hours.

5.6 Temperature Cycle: The components shall remain within the electrical specifications after 5 cycles of high and low temperature testing (one cycle: 80℃ for 30 minutes → 25℃ for 5 minutes→-25℃for 30 minutes)than kept at room temperature for 2 hours.

5.7 Solder-heat Resistance: The components shall remain within the electrical specifications after dipped in the solder at 260℃ for 10±1 seconds, then kept at room temperature for 2 hours. (Terminal must be dipped leaving 1.5 mm from the case).

5.8 Solderability: Solderability of terminal shall be kept at more than 80% after dipped in the solder flux at 230℃±5℃ for 5±1 seconds.

6. Remarks

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.